

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc2621cdd-1#trpbf

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

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**TOTAL MASS (g) : 0.023095**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001091	1000000	47238.921875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.009711	975000	420474.0625		
		Iron (Fe)	7439-89-6	0.000239	24000	10348.3984375		
		Phosphorus (P)	7723-14-0	0.000003	300	129.896209717		
		Zinc (Zn)	7440-66-6	0.000007	700	303.091156006		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.009960</b>	<b>1000000</b>	<b>431255.4375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000455	1000000	19716.6289062		
		<b>External Plating Total:</b>				<b>0.000455</b>	<b>1000000</b>	<b>19716.6289062</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000225	1000000	9742.21484375		
<b>Internal Plating Total:</b>				<b>0.000225</b>	<b>1000000</b>	<b>9742.21484375</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000613	750000	26542.1269531		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000204	250000	8832.94140625		
<b>Die Attach Total:</b>				<b>0.000817</b>	<b>1000000</b>	<b>35375.0664062</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001362	130000	58972.8789062		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.009013	860000	390251.53125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000105	10000	4546.36767578		
		<b>Encapsulation Total:</b>				<b>0.010480</b>	<b>1000000</b>	<b>453770.75</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000067	1000000	2901.01538086		
					<b>TOTAL MASS (g) :</b>	<b>0.023095</b>		